

NC7S32

TinyLogic HS 2-Input OR Gate

Description

The NC7S32 is a single 2-Input high performance CMOS OR Gate. Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation over a broad V_{CC} range. ESD protection diodes inherently guard both inputs and output with respect to the V_{CC} and GND rails. Three stages of gain between inputs and outputs assures high noise immunity and reduced sensitivity to input edge rate.

Features

- Space Saving SC-74A and SC-88A 5-Lead Package
- Ultra Small MicroPak™ Leadless Package
- High Speed: $t_{PD} = 3.5$ ns Typ
- Low Quiescent Power: $I_{CC} < 1$ μ A
- Balanced Output Drive: 2 mA I_{OL} , -2 mA I_{OH}
- Broad V_{CC} Operating Range: 2 V – 6 V
- Balanced Propagation Delays
- Specified for 3 V Operation
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

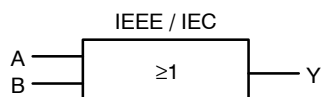


Figure 1. Logic Symbol



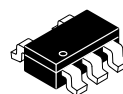
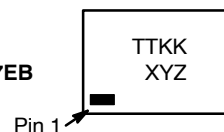
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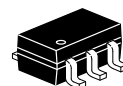
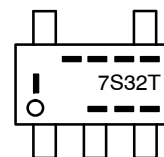
MARKING DIAGRAMS



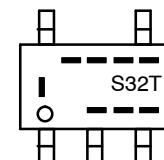
SIP6
CASE 127EB



SC-74A
CASE 318BQ



SC-88A
CASE 419AC-01



TT, 7S32, S32 = Specific Device Code
 KK = 2-Digit Lot Run Traceability Code
 XY = 2-Digit Date Code Format
 Z = Assembly Plant Code
 T = Die Run Code
 --- = Year Coding Scheme
 |-- = Plant Code Identifier
 --- = Eight-Week Datacoding Scheme

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

NC7S32

Pin Configurations

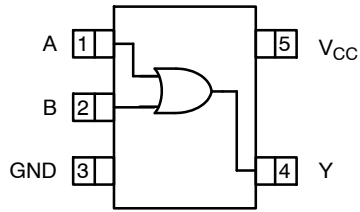


Figure 2. SC-88A and SC-74A (Top View)

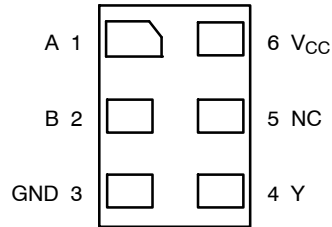


Figure 3. MicroPak (Top Through View)

PIN DESCRIPTIONS

Pin Name	Description
A, B	Inputs
Y	Output
NC	No Connect

FUNCTION TABLE (Y = A + B)

Inputs		Output
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	H

H = HIGH Logic Level
L = LOW Logic Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Supply Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} ≤ -0.5 V	-	-20	mA
		V _{IN} ≥ V _{CC} + 0.5 V	-	+20	
V _{IN}	DC Input Voltage		-0.5	V _{CC} + 0.5	V
I _{OK}	DC Output Diode Current	V _{OUT} < -0.5 V	-	-20	mA
		V _{OUT} > V _{CC} + 0.5 V	-	+20	
V _{OUT}	DC Output Voltage		-0.5	V _{CC} + 0.5	V
I _{OUT}	DC Output Source or Sink Current		-	±12.5	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Output Pin		-	±25	mA
T _{STG}	Storage Temperature		-65	+150	°C
T _J	Junction Temperature		-	+150	°C
T _L	Lead Temperature (Soldering, 10 Seconds)		-	+260	°C
P _D	Power Dissipation in Still Air	SC-74A	-	225	mW
		SC-88A-5	-	190	
		MicroPak	-	327	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

NC7S32

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage		2.0	6.0	V
V _{IN}	Input Voltage		0	V _{CC}	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Times	V _{CC} at 2.0 V	0	20	ns
		V _{CC} at 3.0 V	0	20	
		V _{CC} at 4.5 V	0	10	
		V _{CC} at 6.0 V	0	5	
θ _{JA}	Thermal Resistance	SC-74A	-	555	°C/W
		SC-88A-5	-	659	
		MicroPak	-	382	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

DC ELECTRICAL CHARACTERISTICS

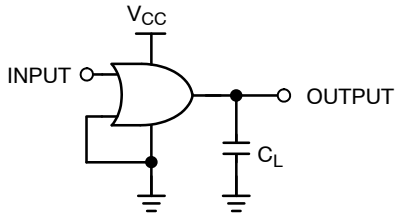
Symbol	Parameter	V _{CC} (V)	Conditions	T _A = +25°C			T _A = -40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
V _{IH}	HIGH Level Input Voltage	2.0 3.0 - 6.0		1.50 0.7 V _{CC}	- -	- -	1.50 0.7 V _{CC}	- -	V
V _{IL}	LOW Level Input Voltage	2.0 3.0 - 6.0		- -	- -	0.50 0.3 V _{CC}	- -	0.50 0.3 V _{CC}	V
V _{OH}	HIGH Level Output Voltage	2.0 3.0 4.5 6.0	I _{OH} = -20 μA V _{IN} = V _{IH}	1.90 2.90 4.40 5.90	2.0 3.0 4.5 6.0	- - - -	1.90 2.90 4.40 5.90	- - - -	V
		3.0 4.5 6.0	V _{IN} = V _{IH} I _{OH} = -1.3 mA I _{OH} = -2.0 mA I _{OH} = -2.6 mA	2.68 4.18 5.68	2.85 4.35 5.85	- - -	2.63 4.13 5.63	- - -	V
V _{OL}	LOW Level Output Voltage	2.0 3.0 4.5 6.0	I _{OL} = 20 μA V _{IN} = V _{IL}	- - - -	0.0 0.0 0.0 0.0	0.10 0.10 0.10 0.10	- - - -	0.10 0.10 0.10 0.10	V
		3.0 4.5 6.0	V _{IN} = V _{IL} I _{OL} = 1.3 mA I _{OL} = 2.0 mA I _{OL} = 2.6 mA	- - -	0.1 0.1 0.1	0.26 0.26 0.26	- - -	0.33 0.33 0.33	V
I _{IN}	Input Leakage Current	6.0	V _{IN} = V _{CC} , GND	-	-	±0.1	-	±1.0	μA
I _{CC}	Quiescent Supply Current	6.0	V _{IN} = V _{CC} , GND	-	-	1.0	-	10.0	μA

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	Conditions	T _A = +25°C			T _A = -40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay (Figure 4, 6)	5.0	C _L = 15 pF	-	3.5	15	-	-	ns
		2.0	C _L = 50 pF	-	20	100	-	125	ns
		3.0		-	12	27	-	35	
		4.5		-	8	20	-	25	
6.0	-	7	17	-	21				
t _{TLH} , t _{THL}	Output Transition Time (Figure 4, 6)	5.0	C _L = 15 pF	-	3.0	10	-	-	ns
		2.0	C _L = 50 pF	-	25	125	-	155	ns
		3.0		-	16	35	-	45	
		4.5		-	11	25	-	30	
6.0	-	9	21	-	26				
C _{IN}	Input Capacitance	Open		-	2	10	-	10	pF
C _{PD}	Power Dissipation Capacitance (Figure 5)	5.0	(Note 2)	-	6	-	-	-	pF

2. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression:
 $I_{CCD} = (C_{PD})(V_{CC})(f_{IN}) + (I_{CCstatic})$.

AC Loading and Waveforms



C_L includes load and stray capacitance
 Input PRR = 1.0 MHz; t_w = 500 ns

Figure 4. AC Test Circuit

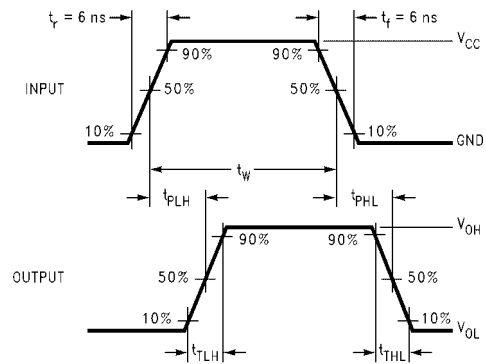
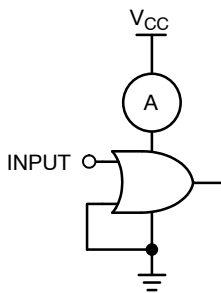


Figure 6. AC Waveforms



Input = AC Waveforms;
 PRR = Variable; Duty Cycle = 50%.

Figure 5. ICCD Test Circuit

NC7S32

ORDERING INFORMATION

Part Number	Top Mark	Package Description	Shipping [†]
NC7S32M5X	7S32	SC-74A	3000 / Tape & Reel
NC7S32P5X	S32	SC-88A	3000 / Tape & Reel
NC7S32L6X	TT	SIP6, MicroPak	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



SIP6 1.45X1.0
CASE 127EB
ISSUE O

DATE 31 AUG 2016



NOTES:

1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-2009
4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY OTHER LINE IN THE MARK CODE LAYOUT.

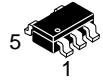
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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

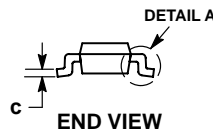
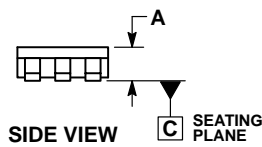
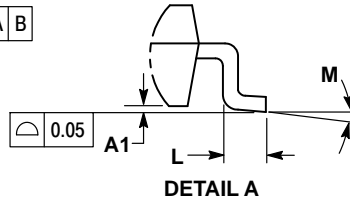
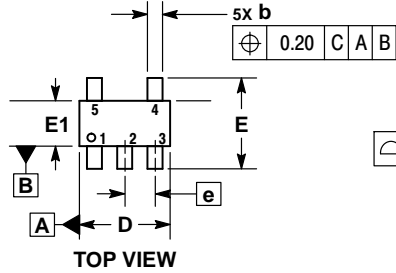
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SCALE 2:1

SC-74A CASE 318BQ ISSUE B

DATE 18 JAN 2018

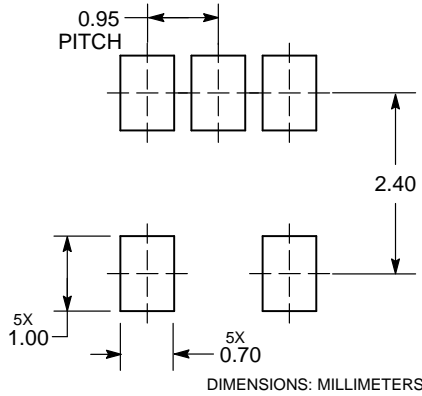


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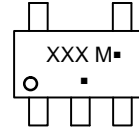
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

DIM	MILLIMETERS	
	MIN	MAX
A	0.90	1.10
A1	0.01	0.10
b	0.25	0.50
c	0.10	0.26
D	2.85	3.15
E	2.50	3.00
E1	1.35	1.65
e	0.95 BSC	
L	0.20	0.60
M	0°	10°

RECOMMENDED SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

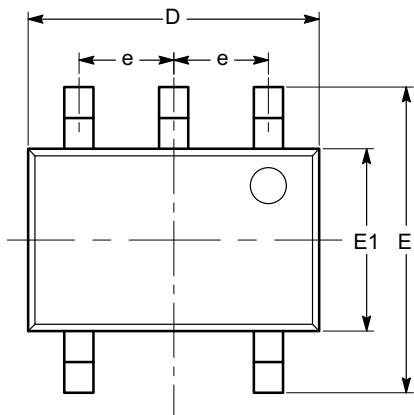
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SC-74A	PAGE 1 OF 2



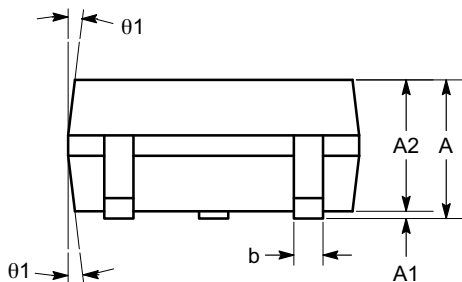
SC-88A (SC-70 5 Lead), 1.25x2
CASE 419AC-01
ISSUE A

DATE 29 JUN 2010

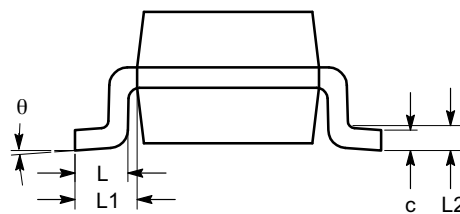


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.80		1.10
A1	0.00		0.10
A2	0.80		1.00
b	0.15		0.30
c	0.10		0.18
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e	0.65 BSC		
L	0.26	0.36	0.46
L1	0.42 REF		
L2	0.15 BSC		
θ	0°		8°
θ_1	4°		10°



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-203.

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